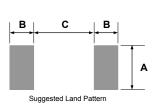
MGDQ1

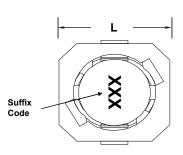


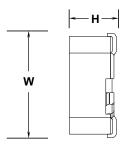
3003 9th Avenue SW PO Box 50 Watertown, SD 57201 Toll free: 888-978-2638 Ph: 605-886-3326 Fax: 605-886-8995

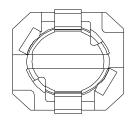


Low Profile, High Current Power Inductors









Series	Maximum Dimensions				Reference Dimensions					
Number	Units	L	w	Н	Х	Y	Z	Α	В	С
MGDQ1	inches	0.256"	0.272"	0.118"	0.181"	0.043"	0.063"	0.069"	0.049"	0.171"
mose;	[mm]	[6.50]	[6.90]	[3.00]	[4.60]	[1.10]	[1.60]	[1.75]	[1.25]	[4.35]

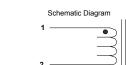
- High energy storage and low resistance
- Reliable surface mounting, flat top for pick and place.
- Smaller real estate than other common inductors.
- Robust temperature deflection to prevent damage during solder reflow.

 • Tape and Reel mechanical specifications
- available upon request.
- Operating Temperature -40°C to +85°C.
- Highly resistive core for EMI suppression applications.

Notes:

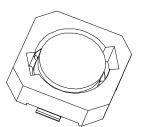
- Inductance measured at 100kHz and 250mVrms.
- Isat is a maximum applied AC + DC current.
- Isat current is applied to produce a typical 35% drop in nominal inductance.

 Tolerance suffix of M = ±20%.
- DCR is a maximum at 20°C.

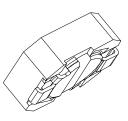


RoHS Compliant

(B0) 260°C Maximum reflow temperature per J-STD020 Terminal Plating is Gold Flash over Ni

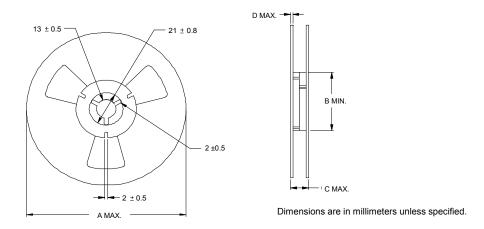






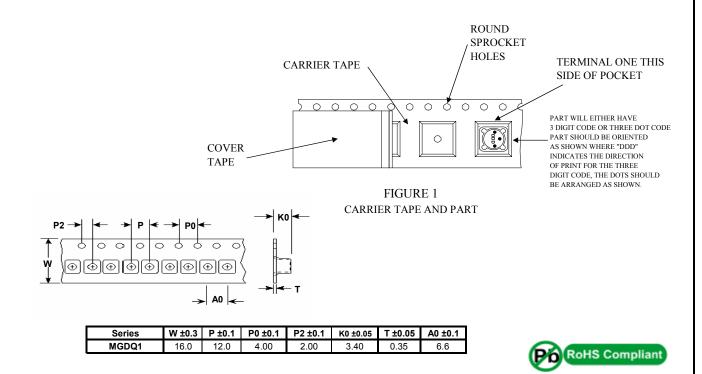
MGDQ1							
Lead Free	L	DCR	I _{SAT}	Tolerance			
Part Number	μH	Ω	Α	Suffix			
MGDQ1-00001	3.3	0.068	1.940	M			
MGDQ1-00002	4.7	0.080	1.630	M			
MGDQ1-00003	5.5	0.096	1.400	M			
MGDQ1-00004	10.0	0.15	1.10	M			
MGDQ1-00005	12.0	0.20	1.00	M			
MGDQ1-00006	15.0	0.23	0.90	M			
MGDQ1-00007	18.0	0.27	0.80	M			
MGDQ1-00008	22.0	0.34	0.74	M			
MGDQ1-00009	27.0	0.38	0.66	M			
MGDQ1-00010	33.0	0.45	0.59	M			
MGDQ1-00011	39.0	0.49	0.54	M			
MGDQ1-00012	47.0	0.69	0.50	M			
MGDQ1-00013	56.0	0.78	0.46	M			
MGDQ1-00014	68.0	1.07	0.42	M			
MGDQ1-00015	82.0	1.21	0.38	M			
MGDQ1-00016	100.0	1.39	0.34	M			
MGDQ1-00017	120.0	1.90	0.31	M			
MGDQ1-00018	150.0	2.18	0.28	M			
MGDQ1-00019	180.0	2.77	0.26	M			
MGDQ1-00020	220.0	3.12	0.23	M			
MGDQ1-00021	270.0	4.38	0.22	M			
MGDQ1-00022	330.0	4.94	0.19	M			

Specifications subject to change



Series			Reel dime	Reel	Carton (Box)	Packaging		
Number	Units	Α	В	С	D	Qty	Qty.	Specification
MGDQ1	in.	14.17"	3.94"	0.88"	0.098"	1500	9000	00 0043
MIGDQI	[mm]	[360]	[100.0]	[22.4]	[2.50]	1500	3000	90-0043

PACKAGING NOTE: Only pressure sensitive cover tape is to be used.



O (D I : O :E: (:	Series Revision		
Customer Packaging Specifications For Print Distribution to Customers	MGDQ1 E		
	Sheet 2 of 3		

ltem	Specification	Test Me	Test Method/Condition				
Environmental Static Humidity	After exposure part remains within specified electrical parameters for L, Q and DCR.		Precondition at 25°C for 60 minutes. Expose parts to an environment of +40°C with 90 to 95% R.H. for 240 hours.				
Storage Life	After exposure part remains within specified electrical parameters for L, Q and DCR.		nvironment of 85°C 85% R.h parts to dry for 4 hours befo				
Temperature Cycle	After exposure part remains within specified electrical parameters for L, Q and DCR.	30 minutes exposure 30 minutes exposure					
Temperature Shock	After exposure part remains within specified electrical parameters for L, Q and DCR.	30 minutes exposure 30 minutes exposure		atures			
IR Reflow B0	10 seconds at 260°C max. (B0 Post test parts shall p	pass all electrical specification ble signs of solder flow or le	ons after reflow.			
General Storage Temperature Range	-40°C to +85°C						
Operating Temperature Range	-40°C to +85°C						
Flammability	IEC 695-2-2	Withstands needle-fla	ame test				
Other							
Vibration	After exposure part remains within specified electrical parameters for L, Q and DCR.	7 - 30 Hz constant ac 31 - 50 Hz constant d	of the following: blacement of 0.75 inches, 5 celeration of 1.5 Gs, 10 min isplacement of 0.33 inches, acceleration of 1.2 Gs, 10 n	utes 5 minutes			
Mechanical Shock	After exposure part remains within specified electrical parameters for L, Q and DCR.	MGDQ1 Series - 500	Gs per axis, 2 directions				
Solderability	Wetting shall cover 90% minimum of each termination	Dip pads in RMA flux, 63/37 solder (Sn/Pb) at 232°C for 5 seconds ±2 seconds.					
Component Adhesion (Push Test)	Component shall withstand 6 lb. push force minimum without delaminating from mounting surface.	Apply and measure fo	orce with a digital force gaug	ge set.			
Resistance to Solvent		Withstands 6 minutes	s of alcohol.				
		Withstands 3 minutes	s forced spray Freon TMS				
Chemical Ionic Contamination	Conductivity: pH: Chlorides: Sodium: Potassium:	11 μOhms/cm maxim 5.5 to 9 65 ppm maximum 20 ppm maximum 10 ppm maximum	um Po RoHS Cor	mpliant			
			Series	Revision			
For Pri	nt Distribution to Custo	omers	MGDQ1	В0			

Sheet 3 of 3